

Call for Papers

ICEP-IAAC 2025

2025 International Conference on Electronics Packaging
and iMAPS All Asia Conference

Date: April 15 - 19, 2025 "On-site Only"

Venue: Wakasato Municipal Cultural Hall, Nagano, Japan

Sponsor: The Japan Institute of Electronics Packaging (JIEP)

Technical Co-Sponsors: IEEE EPS, IEEE EPS Japan Chapter,
iMAPS, SMTA

Major Topics

Advanced Packaging

- 2.xD/3D, TSV/TGV
- Substrates/interposers/RDL
- Fan-out/in packaging
- Wafer/panel level packaging
- Automotive and IoT applications
- High-performance computing
- Heterogeneous integration technologies
- Chiplet packaging
- Hybrid bonding
- Other related technologies

Emerging Technologies

- Health/medical care and cosmetics devices
- Stretchable/flexible electronics
- Sensor and MEMS/NEMS/MOEMS packaging
- Batteries and eco-friendly devices
- Advanced MEMS/NEMS/MOEMS technologies
- Packaging for quantum computing
- Other related technologies

High-Speed, Wireless & Components

- 3D-printed components
- Antennas, RFs, and sensor modules
- Highspeed applications (5G, LTE etc.)
- Automotive and IoT applications
- Other related technologies

Power Electronics

- Power device and module fabrication (HEMT, diode, IPM etc.)
- Advanced Inverter & converter
- Super capacitor
- Harsh environment tolerant device & module
- Si-based MOSFET, BJT, IGBT
- Other relating technologies

Thermal Management

- Advanced cooling technologies
- Thermal management structures (heat sinks, pipes, etc.)
- Simulation, measurement, and evaluation methods
- Other related technologies

Interconnections

- Interconnection methods (flip-chip, wire-bonding etc.)
- 2.xD/3D, TSV/TGV, fan-out/in interconnections
- Embedded systems
- Power electronics interconnections
- Bio/medical and eco-friendly devices
- Hybrid bonding
- Other related technologies

Materials and Processes

- Homo/heterogeneous bonding/assembly
- Substrates, interposers and panels
- Metallic materials & processes (plating, soldering etc.)
- Organic semiconductors (OLED, OFET, OPV etc.)
- Power electronic/battery materials & processes
- Optoelectronic materials & processes
- Additive manufacturing (compound, paste, 3D printing etc.)
- Die to Wafer, Wafer to Wafer, Debonding
- Other related technologies

Design, Modeling, and Reliability

- 2.xD/3D, TSV/TGV, WLCSP, Fan-out/in
- Advanced reliability evaluation (PDfR etc.)
- High performance board design
- Novel test methods and life models (LCA, TCAD etc.)
- Other related technologies

Optoelectronics

- 3D/silicon photonics technologies
- Optical connectors, waveguides, & transceivers
- Device fabrication (LED, laser, sensor, etc.)
- Mid/on-board module fabrication
- Optical wafer/chip-scale packaging
- Co-packaged optics
- Other related technologies

Other Upcoming Technologies

- New system concept & design
- Any other topics related to ICEP scope

Please turn over.

Important datesAbstract submission open: **September 1, 2024**Abstract deadline: **October 31, 2024**Notification of acceptance: **December 15, 2024**Final manuscript deadline: **January 31, 2025**

- Please submit your abstract using the template available at the conference website. <https://www.jiep.or.jp/icep/> You must include the novel, original, and unpublished contents and state the purposes, methods, results, and conclusions clearly in the abstract.
- Once an abstract has been accepted, a **final 2 pages paper** in double column format will be requested by the due date.
- Accepted papers will be submitted for inclusion into IEEE Xplore as well as other Abstracting and Indexing (A&I) databases (EI Compendex and INSPEC).
- The authors are **required to release the copyright** of all submitted contents in their final manuscripts. For details, visit: <https://ux.nu/o27ui>
- Authors of presented papers are strongly encouraged to submit their full paper (4-10 pages) to the Transactions of The Japan Institute of Electronics Packaging (a peer-reviewed international journal, <https://www.jstage.jst.go.jp/browse/jiepeng/-char/en>).
- IEEE reserves the right to exclude a paper from distribution after the conference, including IEEE Xplore® Digital Library, if the paper is not presented by the author at the conference.

Outstanding Technical Paper Award

Description: This award recognizes the outstanding papers on electronics packaging presented at ICEP. The award will be given to the presenting author and co-authors of the outstanding papers.

Funding: The award is sponsored by JIEP.

Eligibility: The presenter must be listed as one of the paper's authors. Conference papers must be submitted on or before the due date.

Basis for Judging: Papers are judged based on technical merit, originality, relevance and potential impact on the field, quality of the written paper, and quality of the conference presentation.

IEEE EPS Japan Chapter Young Award

Description: This award recognizes the excellent papers on electronics packaging presented by young scientists and engineers at ICEP. This award will be given to the presenting author of the excellent papers.

Funding: The award is sponsored by IEEE EPS Japan Chapter.

Eligibility: The presenter must be listed as the paper's first author. The presenter must be younger than 35 on December 31 of the presentation year. Previous winners of this award are not eligible. Conference papers must be submitted on or before the due date. The award recipient must be a member of IEEE and EPS at the time the award is received.

Basis for Judging: Papers are judged based on technical merit, originality, relevance and potential impact on the field, quality of the written paper, and quality of the conference presentation.

JIEP Poster Award

Description: This award recognizes the excellent work by poster presenters at ICEP. The award will be given to the presenting author and co-authors of the excellent papers.

Funding: The award is sponsored by JIEP.

Eligibility: The presenter must be listed as one of their paper's authors. Conference papers must be submitted on or before the due date.

Basis for Judging: Papers are judged based on technical merit, originality, relevance and potential impact on the field, quality of the written paper, and quality of the conference presentation.

ICEP is the largest international conference on electronic packaging in Japan, attracting more than 600 attendees and hosting about 35 technical sessions. ICEP provides a strong platform to demonstrate your technologies and products as well as expand your customer network. It is jointly sponsored by JIEP, IEEE EPS, IEEE EPS Japan Chapter, iMAPS, and SMTA. The conference has technical sessions covering a wide range of topics including advanced packaging, design, modeling and reliability, emerging technologies, high-speed, wireless & components, interconnections, materials and processes, optoelectronics, power electronics integration, and thermal management. Since its inauguration in 2001, ICEP has developed into a highly reputed electronics packaging conference in Japan, attended by world-renowned experts in all aspects related to packaging technologies from all over the world. In 2025, International Conference on Electronics Packaging joined with iMAPS All Asia Conference (ICEP-IAAC 2025).

Registration Fees

Member of JIEP / IEEE / IMAPS: 45,000 JPY

Non-Member: 60,000 JPY

Students: 20,000 JPY

Registration Fees include Reception and Proceedings.

Sponsorship Opportunities

We invite you to be a sponsor, which entitles your company to be exposed to the attendees in and outside the conference rooms. The sponsorship for ICEP 2025 ranges from 500,000 yen to 50,000 yen. As a sponsor, your company's name and logo will be published in the conference's official program and will appear on the ICEP website as well as various conference banners. Furthermore, a tabletop exhibition booth is available for the diamond, platinum, and gold sponsors to demonstrate and promote your products/services. Please contact the conference secretary for details.

Agenda

April 15th (afternoon): IAAC special session

April 16th: Keynote lectures, Award ceremony, Welcome reception

April 17th: Technical sessions, Sponsor exhibition's party

April 18th: Technical sessions

April 19th: Excursion

Organizing Committee

General Chair: T. Sakai, TSMC Japan 3DIC R&D Center

General Vice Chairs: Y. Morikawa, ULVAC

R. Endo, Rapidus

T. Ishigure, Keio University

Contact

Secretariat of ICEP 2025

The Japan Institute of Electronics Packaging (JIEP)

E-mail: icep2025@jiep.or.jpURL: <https://www.jiep.or.jp/icep/>